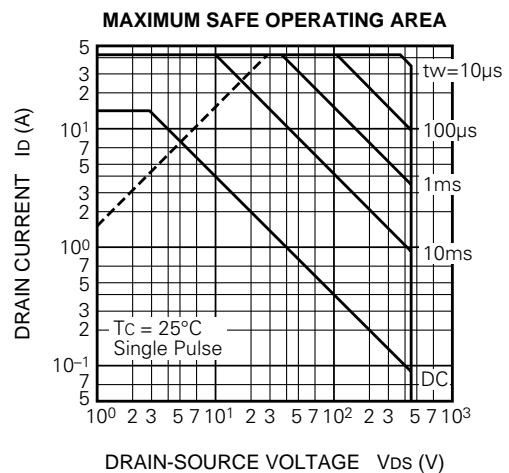
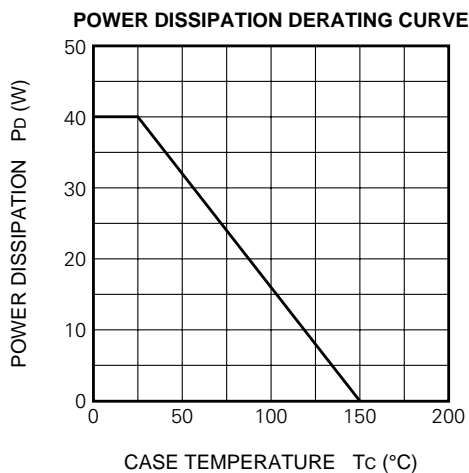


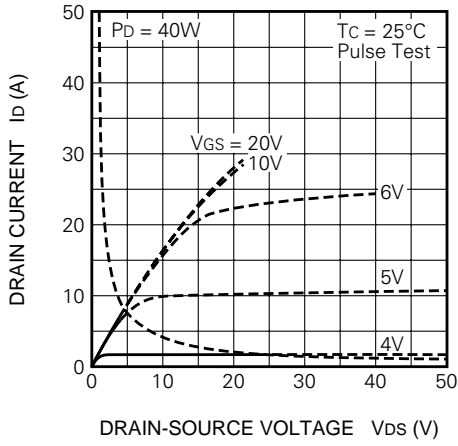
ELECTRICAL CHARACTERISTICS (Tch = 25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V (BR) DSS	Drain-source breakdown voltage	Id = 1mA, VGS = 0V	450	—	—	V
V (BR) GSS	Gate-source breakdown voltage	IG = ±100μA, VDS = 0V	±30	—	—	V
IGSS	Gate-source leakage current	VGS = ±25V, VDS = 0V	—	—	±10	μA
IDSS	Drain-source leakage current	VDS = 450V, VGS = 0V	—	—	1	mA
VGS (th)	Gate-source threshold voltage	Id = 1mA, VDS = 10V	2	3	4	V
rDS (ON)	Drain-source on-state resistance	Id = 7A, VGS = 10V	—	0.50	0.65	Ω
VDS (ON)	Drain-source on-state voltage	Id = 7A, VGS = 10V	—	3.50	4.55	V
yfs	Forward transfer admittance	Id = 7A, VDS = 10V	4.5	7.0	—	S
Ciss	Input capacitance	VDS = 25V, VGS = 0V, f = 1MHz	—	1500	—	pF
Coss	Output capacitance		—	180	—	pF
Crss	Reverse transfer capacitance		—	30	—	pF
td (on)	Turn-on delay time		—	30	—	ns
tr	Rise time	VDD = 200V, Id = 7A, VGS = 10V, RGEN = RGS = 50Ω	—	50	—	ns
td (off)	Turn-off delay time		—	130	—	ns
tf	Fall time		—	50	—	ns
VSD	Source-drain voltage	IS = 7A, VGS = 0V	—	1.5	2.0	V
Rth (ch-c)	Thermal resistance	Channel to case	—	—	3.13	°C/W
trr	Reverse recovery time	IS = 14A, dis/dt = -100A/μs	—	—	150	ns

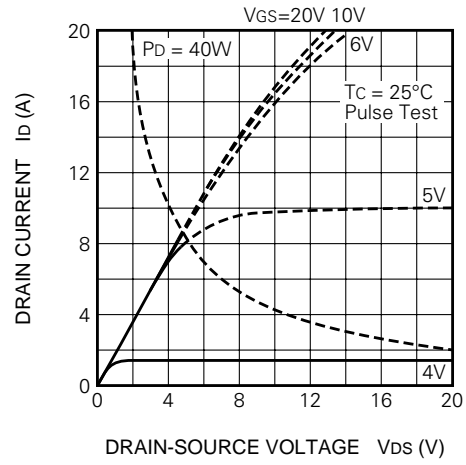
PERFORMANCE CURVES



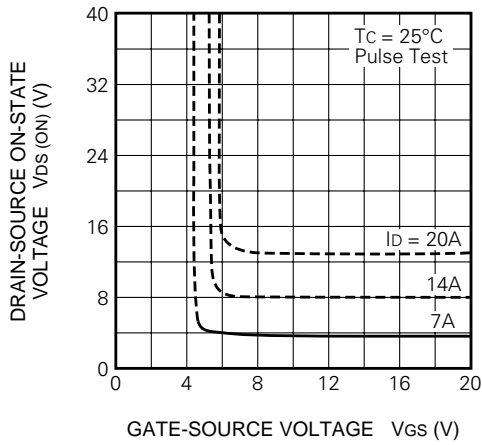
OUTPUT CHARACTERISTICS (TYPICAL)



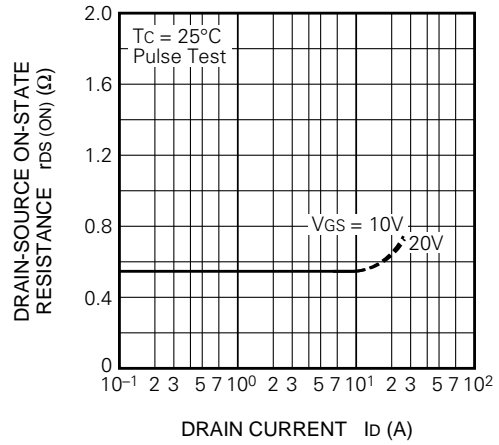
OUTPUT CHARACTERISTICS (TYPICAL)



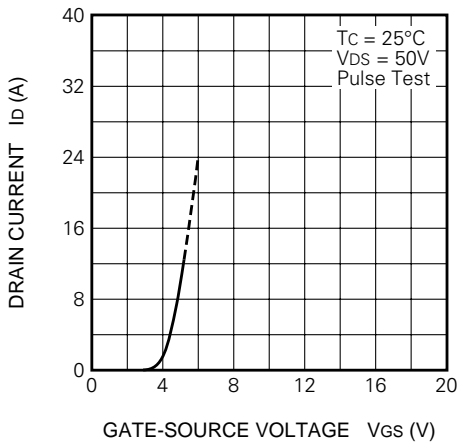
ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)



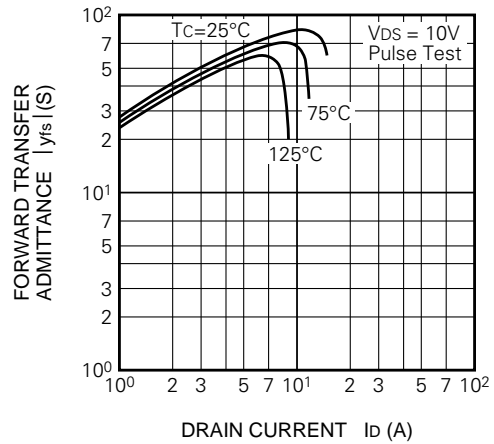
ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)



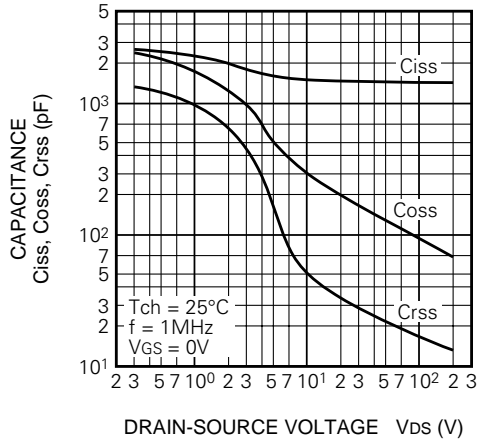
TRANSFER CHARACTERISTICS (TYPICAL)



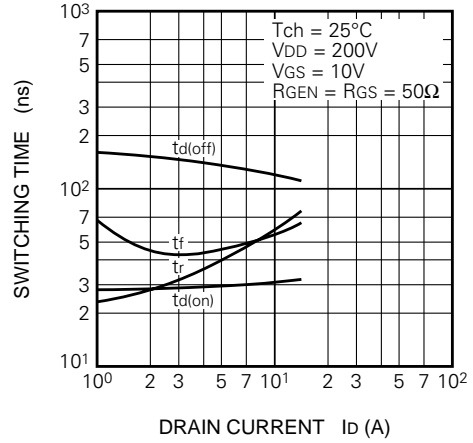
FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)



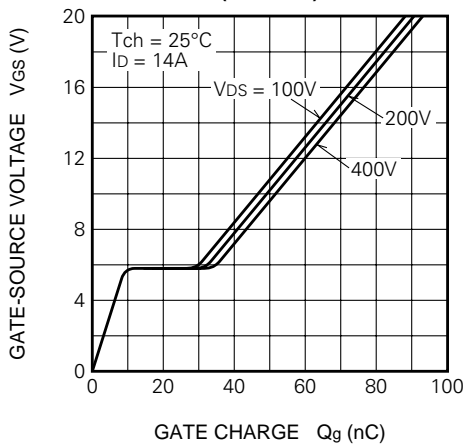
CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)



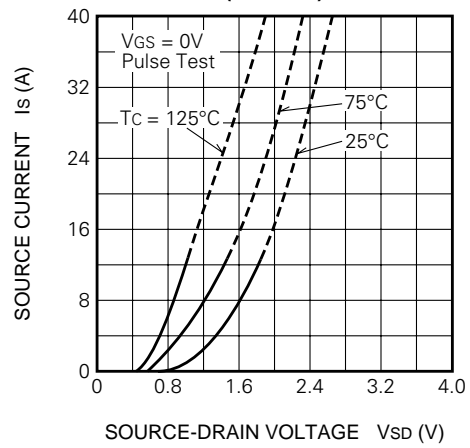
SWITCHING CHARACTERISTICS (TYPICAL)



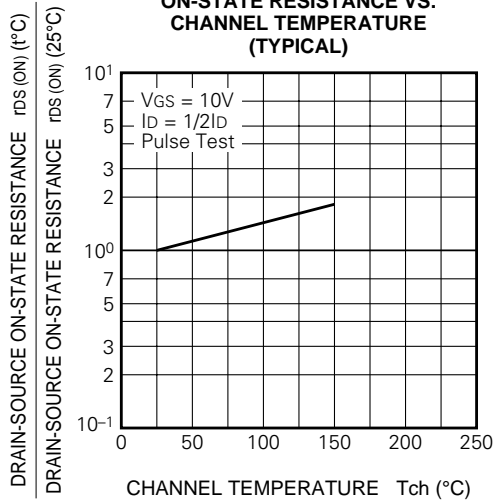
GATE-SOURCE VOLTAGE VS. GATE CHARGE (TYPICAL)



SOURCE-DRAIN DIODE FORWARD CHARACTERISTICS (TYPICAL)



ON-STATE RESISTANCE VS. CHANNEL TEMPERATURE (TYPICAL)



THRESHOLD VOLTAGE VS. CHANNEL TEMPERATURE (TYPICAL)

